

**OptiMOS™-5 Power-Transistor**

**Features**

- OptiMOS™ - power MOSFET for automotive applications
- N-channel - Enhancement mode - Logic Level
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- Green product (RoHS compliant)
- 100% Avalanche tested

**Quality Features**

- Infineon Automotive Quality
- Extended qualification beyond AEC Q101
- Enhanced testing
- Advanced adhesion against delamination
- Complementary testing for board level reliability


**Advanced adhesion**

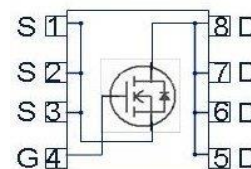
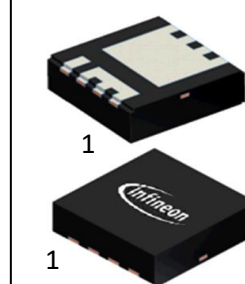
**Robust**

**Enhanced tested**

Type	Package	Marking
IAUZ20N08S5L300	PG-TSDSON-8	5N8L300

**Product Summary**

$V_{DS}$	80	V
$R_{DS(on)}$	30	mΩ
$I_D$	20	A

**PG-TSDSON-8**

**Maximum ratings, at  $T_j=25\text{ °C}$ , unless otherwise specified**

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	$I_D$	$T_C=25\text{ °C}, V_{GS}=10\text{ V}$	20	A
		$T_C=100\text{ °C}, V_{GS}=10\text{ V}^{(1)}$	14	
Pulsed drain current <sup>(1)</sup>	$I_{D,pulse}$	$T_C=25\text{ °C}$	80	
Avalanche energy, single pulse <sup>(1)</sup>	$E_{AS}$	$I_D=10\text{ A}$	20	mJ
Avalanche current, single pulse	$I_{AS}$	-	10	A
Gate source voltage	$V_{GS}$	-	±20	V
Power dissipation	$P_{tot}$	$T_C=25\text{ °C}$	30	W
Operating and storage temperature	$T_j, T_{stg}$	-	-55 ... +175	°C
IEC climatic category; DIN IEC 68-1	-	-	55/175/56	

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

**Thermal characteristics<sup>1)</sup>**

Thermal resistance, junction - case	$R_{thJC}$	-	-	-	5	K/W
Thermal resistance, junction - ambient <sup>2)</sup>	$R_{thJA}$	-	-	40	-	

**Electrical characteristics, at  $T_j=25\text{ °C}$ , unless otherwise specified**
**Static characteristics**

Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{ V}, I_D=1\text{ mA}$	80	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=8\text{ }\mu\text{A}$	1.2	1.6	2.0	
Zero gate voltage drain current	$I_{DSS}$	$V_{DS}=80\text{ V}, V_{GS}=0\text{ V}, T_j=25\text{ °C}$	-	-	1	$\mu\text{A}$
		$V_{DS}=80\text{ V}, V_{GS}=0\text{ V}, T_j=85\text{ °C}^{1)}$	-	-	100	
Gate-source leakage current	$I_{GSS}$	$V_{GS}=20\text{ V}, V_{DS}=0\text{ V}$	-	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=4.5\text{ V}, I_D=10\text{ A}$	-	29.8	41.0	$\text{m}\Omega$
		$V_{GS}=10\text{ V}, I_D=10\text{ A}$	-	22.4	30	
Gate resistance <sup>1)</sup>	$R_G$		-	0.9	-	$\Omega$

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

**Dynamic characteristics<sup>1)</sup>**

Input capacitance	$C_{iss}$	$V_{GS}=0\text{ V}, V_{DS}=40\text{ V},$ $f=1\text{ MHz}$	-	461	599	pF
Output capacitance	$C_{oss}$		-	83	108	
Reverse transfer capacitance	$C_{rss}$		-	7.7	11.6	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=40\text{ V}, V_{GS}=10\text{ V},$ $I_D=20\text{ A}, R_G=3.5\ \Omega$	-	2	-	ns
Rise time	$t_r$		-	1	-	
Turn-off delay time	$t_{d(off)}$		-	5	-	
Fall time	$t_f$		-	3	-	

**Gate Charge characteristics<sup>1)</sup>**

Gate to source charge	$Q_{gs}$	$V_{DD}=40\text{ V}, I_D=10\text{ A},$ $V_{GS}=0\text{ to }10\text{ V}$	-	1.5	1.9	nC
Gate to drain charge	$Q_{gd}$		-	1.8	2.7	
Gate charge total	$Q_g$		-	8.1	10.5	
Gate plateau voltage	$V_{plateau}$		-	3.2	-	V

**Reverse Diode**

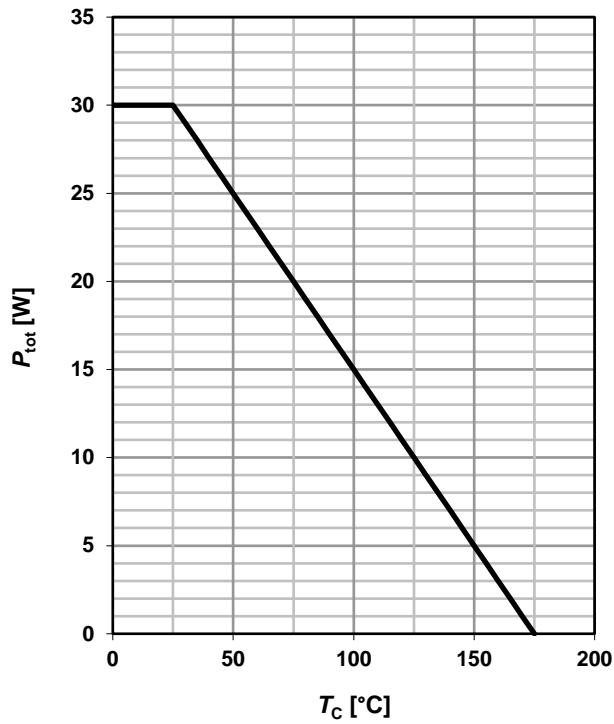
Diode continuous forward current <sup>1)</sup>	$I_S$	$T_C=25\text{ °C}$	-	-	20	A
Diode pulse current <sup>1)</sup>	$I_{S,pulse}$		-	-	43	
Diode forward voltage	$V_{SD}$	$V_{GS}=0\text{ V}, I_F=10\text{ A},$ $T_j=25\text{ °C}$	-	0.9	1.2	V
Reverse recovery time <sup>1)</sup>	$t_{rr}$	$V_R=40\text{ V}, I_F=20\text{ A},$ $di_F/dt=100\text{ A}/\mu\text{s}$	-	29	-	ns
Reverse recovery charge <sup>1)</sup>	$Q_{rr}$		-	20	-	nC

<sup>1)</sup> The parameter is not subject to production test - verified by design/characterization.

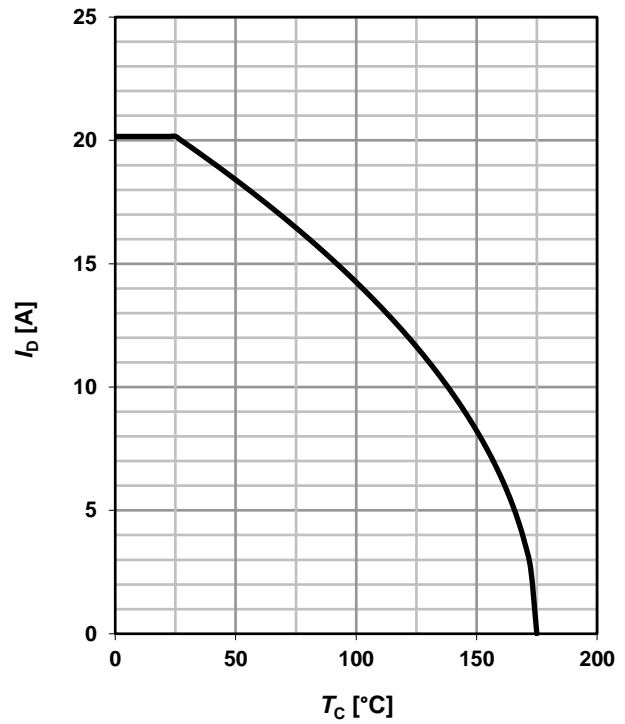
<sup>2)</sup> Device on four layer 2s2p PCB defined in accordance with JEDEC standards (JESD51-5-7).  
PCB is vertical in still air.

**1 Power dissipation**

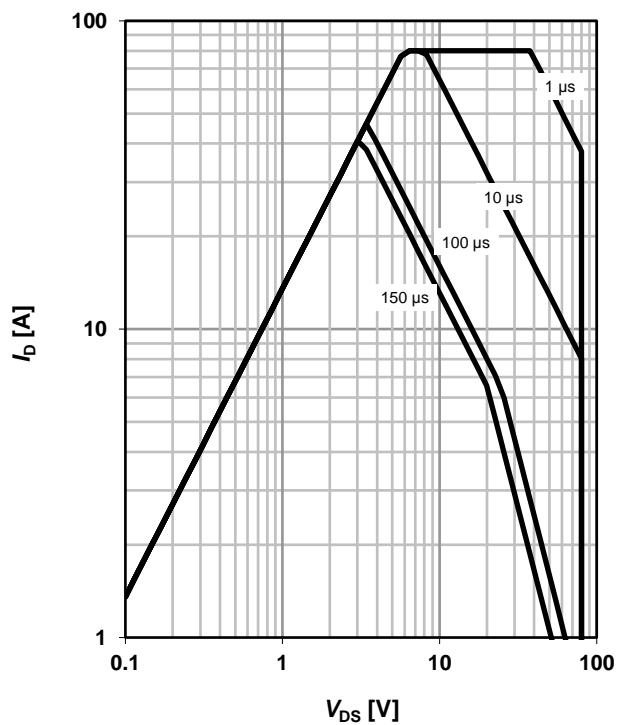
$$P_{\text{tot}} = f(T_C); V_{\text{GS}} \geq 6 \text{ V}$$


**2 Drain current**

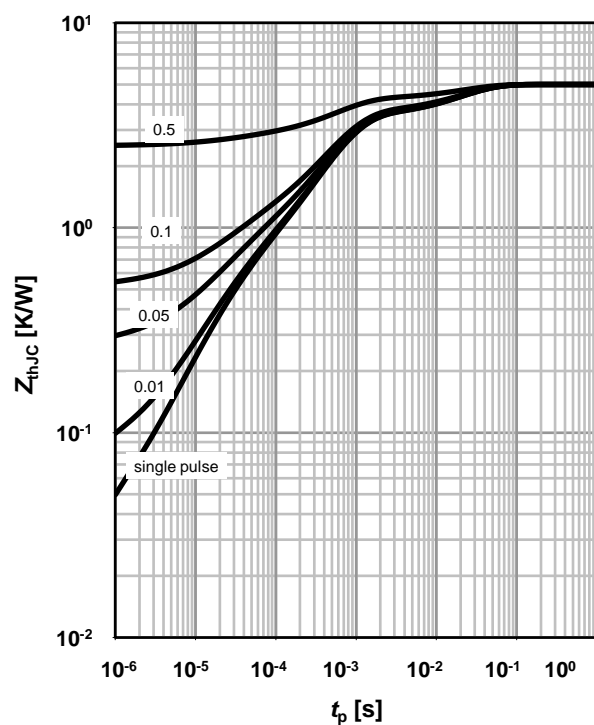
$$I_D = f(T_C); V_{\text{GS}} \geq 6 \text{ V}$$


**3 Safe operating area**

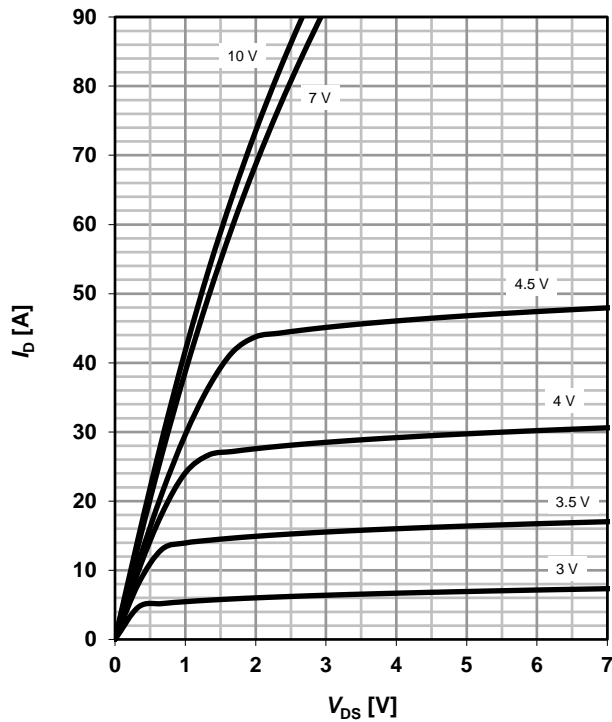
$$I_D = f(V_{\text{DS}}); T_C = 25 \text{ °C}; D = 0$$

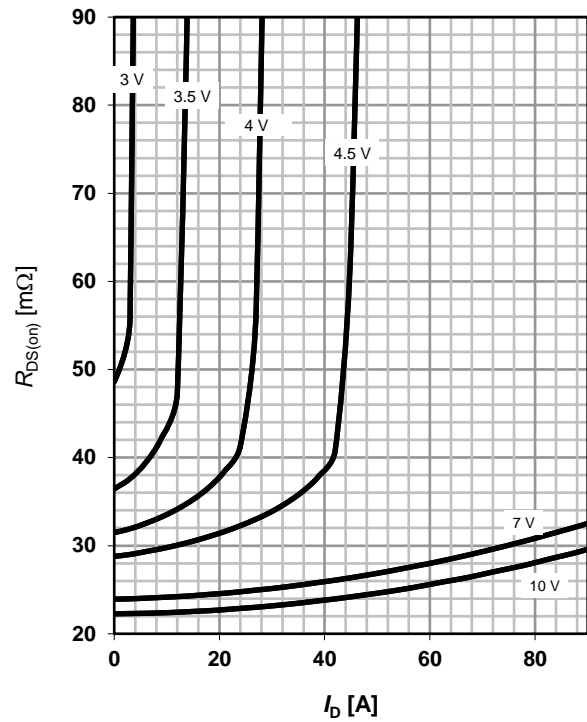
 parameter:  $t_p$ 

**4 Max. transient thermal impedance**

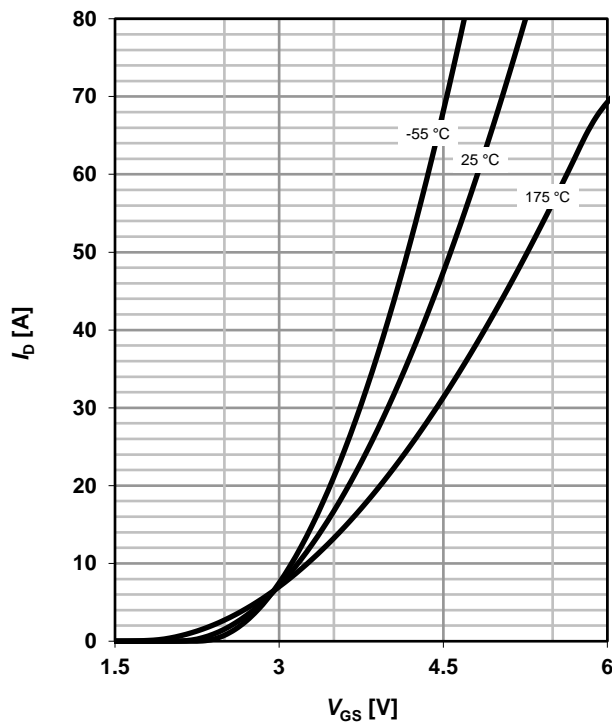
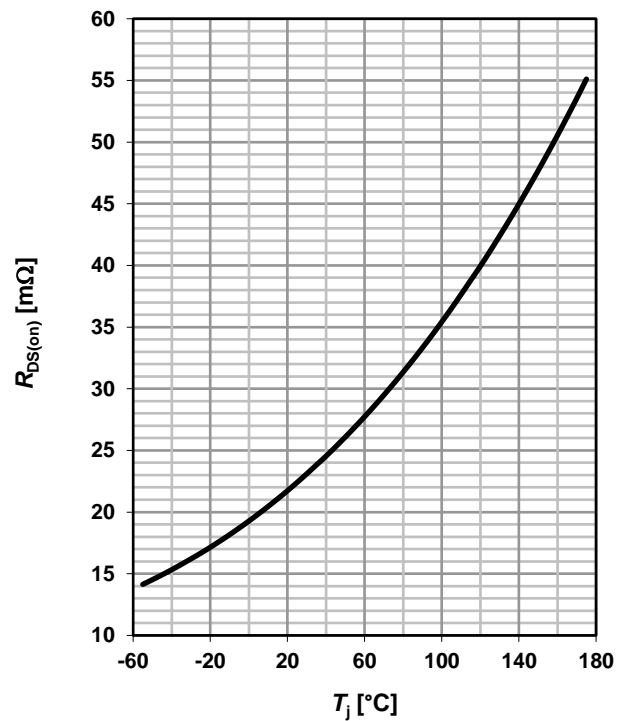
$$Z_{\text{thJC}} = f(t_p)$$

 parameter:  $D = t_p/T$ 


**5 Typ. output characteristics**
 $I_D = f(V_{DS}); T_j = 25\text{ }^\circ\text{C}$ 

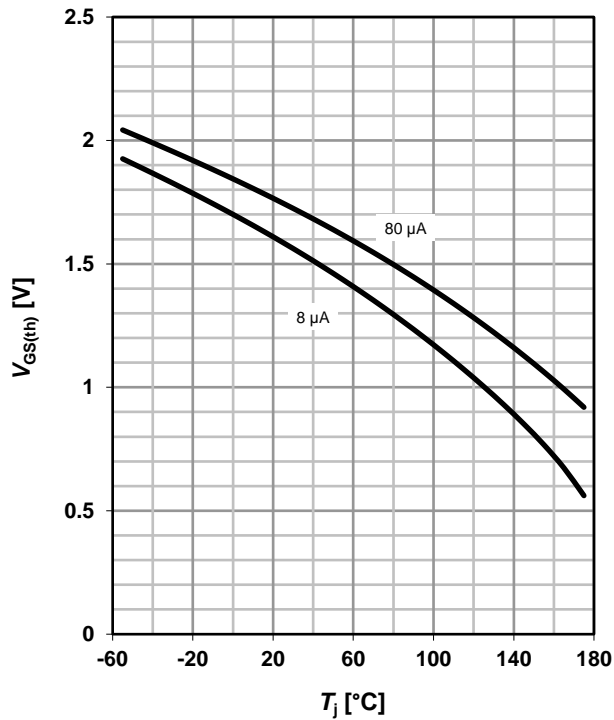
 parameter:  $V_{GS}$ 

**6 Typ. drain-source on-state resistance**
 $R_{DS(on)} = f(I_D); T_j = 25\text{ }^\circ\text{C}$ 

 parameter:  $V_{GS}$ 

**7 Typ. transfer characteristics**
 $I_D = f(V_{GS}); V_{DS} = 6\text{ V}$ 

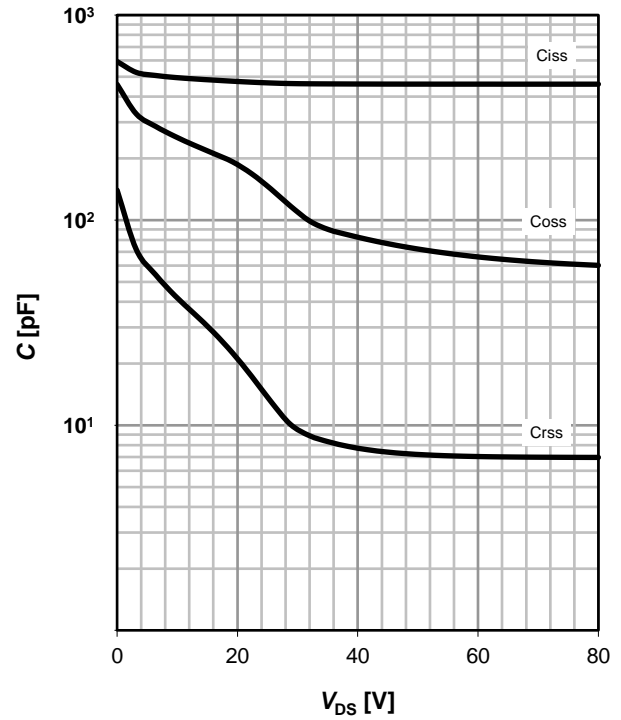
 parameter:  $T_j$ 

**8 Typ. drain-source on-state resistance**
 $R_{DS(on)} = f(T_j); I_D = 10\text{ A}; V_{GS} = 10\text{ V}$ 


**9 Typ. gate threshold voltage**

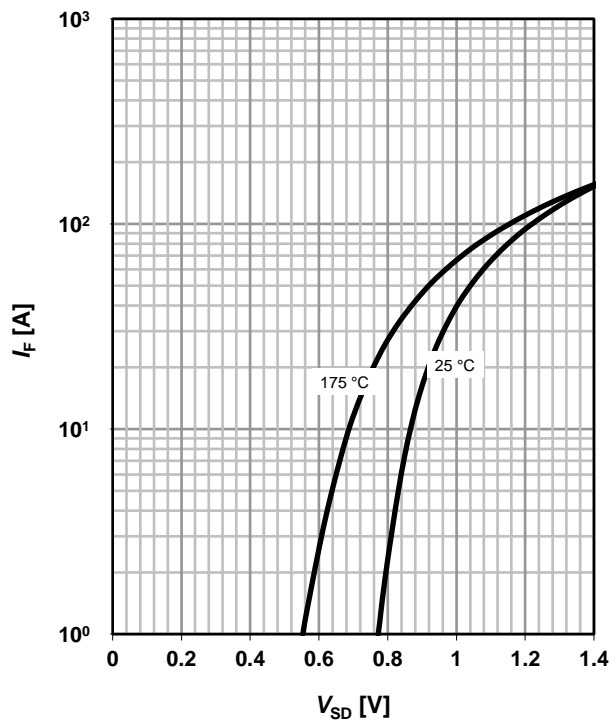
$$V_{GS(th)} = f(T_j); V_{GS} = V_{DS}$$

 parameter:  $I_D$ 

**10 Typ. capacitances**

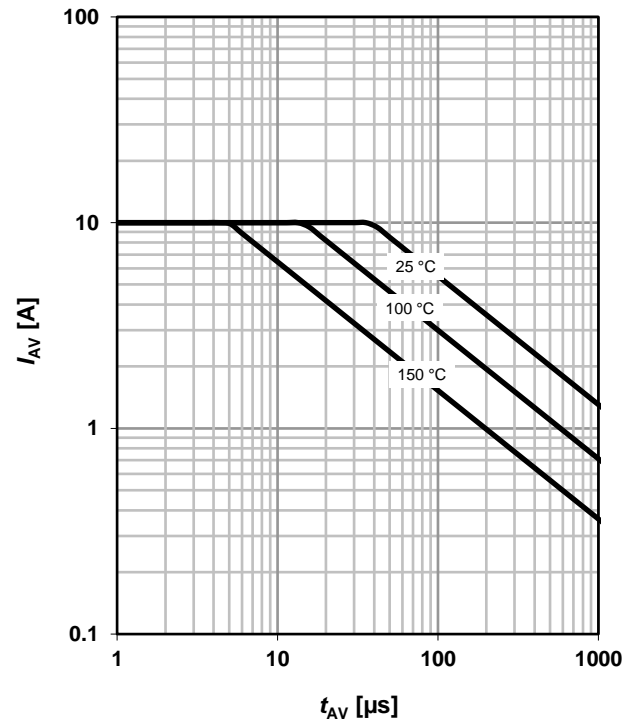
$$C = f(V_{DS}); V_{GS} = 0 V; f = 1 MHz$$


**11 Typical forward diode characteristics**

$$I_F = f(V_{SD})$$

 parameter:  $T_j$ 

**12 Typ. avalanche characteristics**

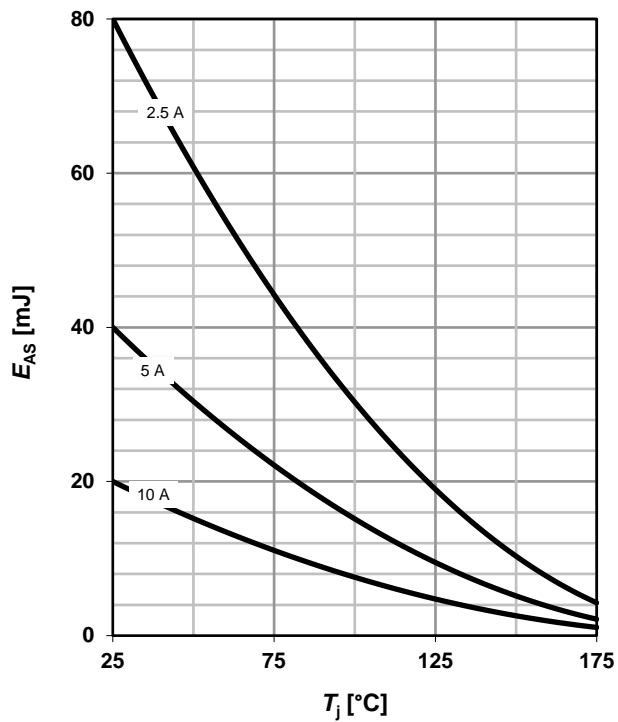
$$I_{AS} = f(t_{AV})$$

 parameter:  $T_{j(start)}$ 


### 13 Typical avalanche energy

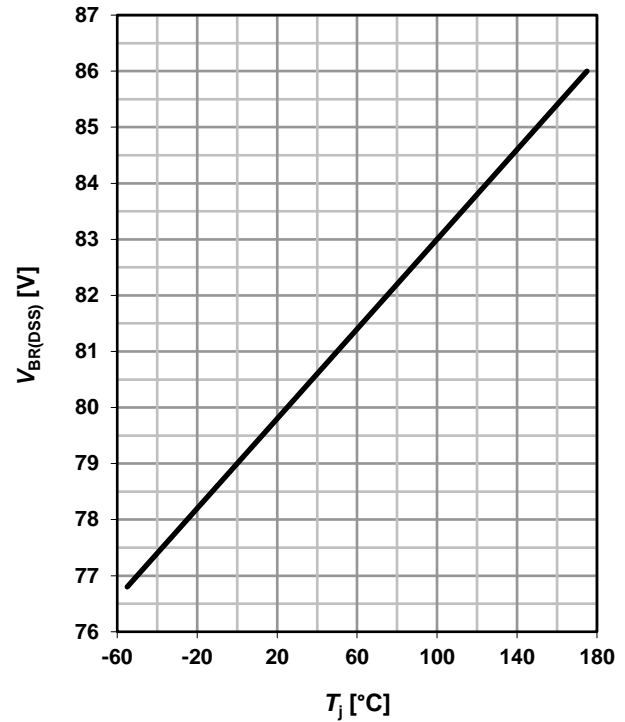
$$E_{AS} = f(T_j)$$

parameter:  $I_D$



### 14 Drain-source breakdown voltage

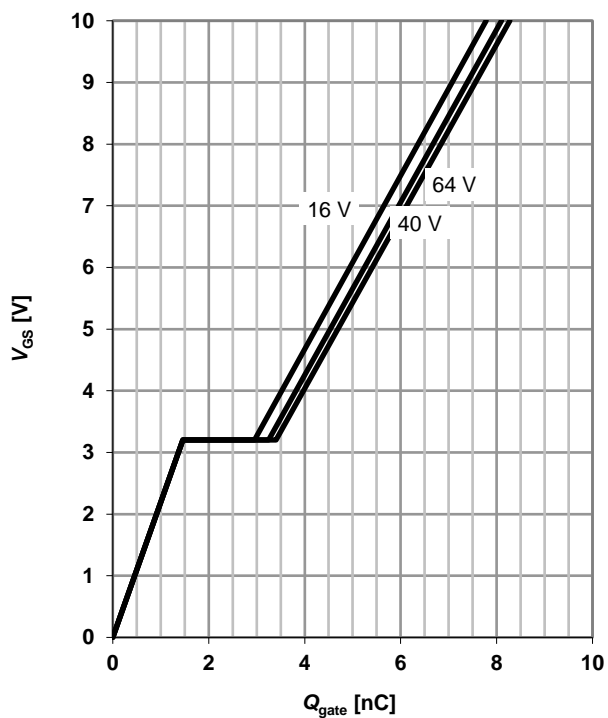
$$V_{BR(DSS)} = f(T_j); I_{D\_typ} = 1 \text{ mA}$$



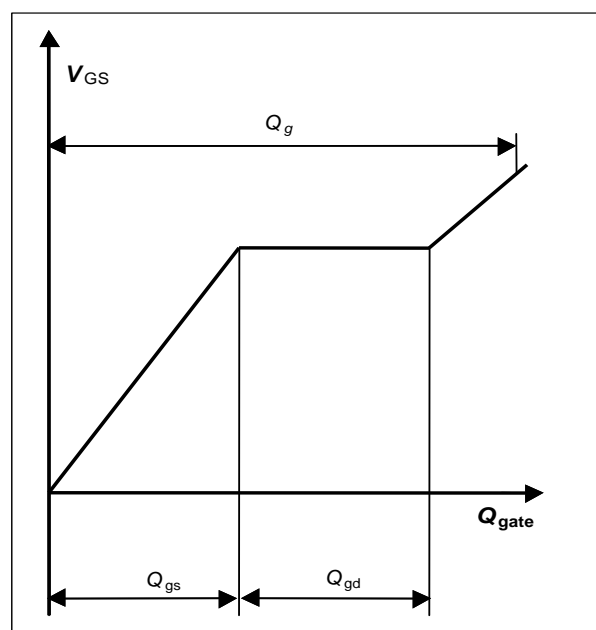
### 15 Typ. gate charge

$$V_{GS} = f(Q_{gate}); I_D = 10 \text{ A pulsed}$$

parameter:  $V_{DD}$



### 16 Gate charge waveforms







**Published by**  
**Infineon Technologies AG**  
**85579 Neubiberg, Germany**

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